Product / Process Change Notification



N° 2019-120-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Transfer of dedicated products in PG-DSO package from Assembly location Unisem Group Ltd. to Infineon Technologies (Malaysia) Sdn. Bhd.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 09. October 2019.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Wolfgang Eder Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg Commercial Register: München HRB 126492

Product / Process Change Notification



N° 2019-120-A

► **Products affected:** Please refer to attached affected product list 1_cip19120_a

Detailed Change Information:

Subject:	Transfer of dedicated products in PG-DSO package from Assembly location Unisem Group Ltd. to Infineon Technologies (Malaysia) Sdn. Bhd. Melaka, Malaysia						
Reason:	On June 28th 2019, the boards of PT Unisem and Unisem Bhd released a written communication to announce the discontinuation of operations of its facility in Batam, Indonesia. The closure date has been stipulated by 30th Sep 2019, NO push out possible						
Description:	<u>Old</u>	New					
BE Assembly location	 Unisem Group Ltd., Indonesia 	 Infineon Technologies (Malaysia) Sdn.Bhd. Melaka, Malaysia 					
Mould compound	 EME 6600 (Halogen containing mold compound) 	 CEL 9220 (Halogen-free mold compound) 					
Marking on device	 Datecode starting with "G" 123456 G 	 Datecode starting with "H" and including LOTCODE 12345678 XXX H — — — — — — — — — — — — — — — — — — —					
	Backside marking:	 No marking on backside 					

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N° 2019-120-A



2019-120-A					
Deekene outline					
Package outline dimensions					
Package thickness [mm] Lead Width [mm] Standoff [mm] Package Width [mm]	 0.1MIN 	 1.35 - 1.55 0.35 - 0.51 0.105 - 0.245 3.80 - 4.00 All other package outline dimensions remain unchanged 			
Product barcode label	Pb free logo	 Pb free and halogen-free logo 			
SP number	Change of According to 1_cip19120_a (referring also to PD_206_19)				
Product Identification:	Internal traceability via Baunumber, Lotnumber, date code and marking External traceability : A. Country of assembly: Change from Indonesia to Malaysia B. Halogen-free logo printed on barcode label Infineon SPMOS TM BoolissPv G (1T): VC926934G05 (1T):				
Impact of Change:	NO change in existing datasheet parameters NO change in quality and reliability. Processes are optimized to meet				
	product performance according to already applied Infineon specification.				
Attachments:	Affected product list 1_cip19120_a.xlsx				
Time Schedule:					
Final qualification report:	30-11-2019				
First samples available:	available				
Intended start of delivery:	30-11-2019 or earlier upon customer approval				

If you have any questions, please do not hesitate to contact your local Sales office.

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PCN N° 2019-120-A Transfer of dedicated products in PG-DSO package from Assembly location Unisem Group Ltd. to Infineon Technologies (Malaysia) Sdn. Bhd.

Sales name	SP number (old)	OPN (old)	SP number (new)	OPN (new)	Package
BSO612CV G	SP000216307	BSO612CVGHUMA1	SP005353855	BSO612CVGXUMA1	PG-DSO-8
BSO613SPV G	SP000216309	BSO613SPVGHUMA1	SP005353854	BSO613SPVGXUMA1	PG-DSO-8
BSO615C G	SP000216311	BSO615CGHUMA1	SP005353856	BSO615CGXUMA1	PG-DSO-8
BSO615N G	SP000216316	BSO615NGHUMA1	SP005353857	BSO615NGXUMA1	PG-DSO-8